SDAS198B - APRIL 1982 - REVISED AUGUST 1995

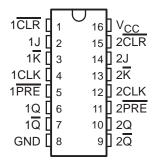
 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY (MHz)	TYPICAL POWER DISSIPATION PER FLIP-FLOP (mW)
'ALS109A	50	6
'AS109A	129	29

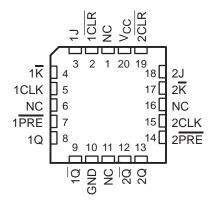
description

These devices contain two independent J-K positive-edge-triggered flip-flops. A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the J and \overline{K} inputs meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the J and \overline{K} inputs can be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding \overline{K} and tying J high. They also can perform as D-type flip-flops if J and \overline{K} are tied together.

SN54ALS109A, SN54AS109A . . . J PACKAGE SN74ALS109A, SN74AS109A . . . D OR N PACKAGE (TOP VIEW)



SN54ALS109A, SN54AS109A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54ALS109A and SN54AS109A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS109A and SN74AS109A are characterized for operation from 0°C to 70°C.

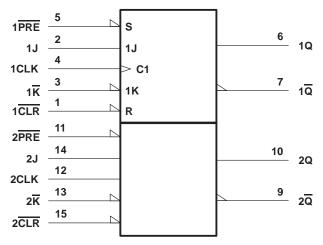
FUNCTION TABLE

			OUTI	PUTS		
PRE	CLR	CLK	J	K	Q	Q
L	Н	Х	Х	Χ	Н	L
Н	L	X	Χ	X	L	Н
L	L	X	Χ	X	H [†]	H [†]
Н	Н	\uparrow	L	L	L	Н
Н	Н	\uparrow	Н	L	Tog	gle
Н	Н	\uparrow	L	Н	Q0	Q0
Н	Н	\uparrow	Н	Н	Н	L
Н	Н	L	Χ	X	Q0	Q0

† The output levels in this configuration are not specified to meet the minimum levels for V_{OH} if the lows at PRE and CLR are near V_{IL} maximum. Furthermore, this configuration is nonstable; that is, it does not persist when either PRE or CLR returns to its inactive (high) level.

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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN54ALS109A	. −55°C to 125°C
SN74ALS109A	0°C to 70°C
Storage temperature range	65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN	54ALS10	9A	SN7	'4ALS10	9A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.7			0.8	V
loh	High-level output current			-0.4			-0.4	mA	
lOL	Low-level output current			4			8	mA	
fclock	Clock frequency		0		30	0		34	MHz
		PRE or CLR low	15			15			
t _w	Pulse duration	CLK high	16.5			14.5			ns
		CLK low	16.5			14.5			
	Outure the electron OLIC	Data	15			15			
t _{su}	Setup time before CLK↑	PRE or CLR inactive	10			10			ns
t _h	Hold time after CLK↑	Data	0			0			ns
TA	Operating free-air temperature	_	-55		125	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN5	4ALS10	9A	SN7	4ALS10	9A		
PA	RAMETER	TEST CO	NDITIONS	MIN	TYP [†]	MAX	MIN	TYP†	MAX	UNIT	
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V	
Vон		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			V _{CC} -2			V	
		457	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	.,	
VOL		V _{CC} = 4.5 V	IOL = 8 mA					0.35	0.5	V	
	CLK, J, or K	V 55V V 7V				0.1			0.1	A	
"	PRE or CLR	$V_{CC} = 5.5 \text{ V},$	$V_I = 7 V$			0.2			0.2	mA	
	CLK, J, or K					20			20		
lн	PRE or CLR	V _{CC} = 5.5 V,	$V_{I} = 2.7 V$			40			40	μΑ	
	CLK, J, or K					-0.2			-0.2		
IIL	PRE or CLR	V _{CC} = 5.5 V,	$V_{I} = 0.4 V$			-0.4			-0.4	mA	
I _O ‡		V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA	
ICC		V _{CC} = 5.5 V,	See Note 1		2.4	4		2.4	4	mA	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _l R _l T _A	UNIT			
	, ,	, ,	SN54AL	S109A	SN74ALS109A		
			MIN	MAX	MIN	MAX	
f _{max}			30		34		MHz
t _{PLH}	PRE or CLR	0	3	17	3	13	
t _{PHL}	PRE OF CLR	Q or Q	5	17	5	15	ns
t _{PLH}	CLK	Q or Q	5	21	5	16	ns
^t PHL	OLK	QUIQ	5	20	5	18	110

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[†] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, Ios. NOTE 1: Icc is measured with J, K, CLK, and PRE grounded, then with J, K, CLK, and CLR grounded.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}		7 V
Input voltage, V _I		7 V
Operating free-air temperature range, T _A :	SN54AS109A	–55°C to 125°C
	SN74AS109A	0°C to 70°C
Storage temperature range		_65°C to 150°C

recommended operating conditions

			SN54AS109A		9A	SN	74AS109)A		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage		2			2			V	
V _{IL}	Low-level input voltage				0.8			0.8	V	
IOH	High-level output current			-2			-2	mA		
l _{OL}	Low-level output current			20			20	mA		
f _{clock} *	Clock frequency		0		90	0		105	MHz	
		PRE or CLR low	4			4				
t _w *	Pulse duration	CLK high	4			4			ns	
		CLK low	5.5			5.5				
	0	Data	5.5			5.5				
t _{su} *	Setup time before CLK↑	PRE or CLR inactive	2			2			ns	
th*	Hold time after CLK↑	Data	0			0			ns	
TA	Operating free-air temperature		-55		125	0		70	°C	

^{*} On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			NETICNE	SN	54AS10	9A	SN	74AS109	9A	
		TEST CONDITIONS			TYP‡	MAX	MIN	TYP‡	MAX	UNIT
۷ıK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V
Vон		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			V _{CC} -2			V
VOL		$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.25	0.5		0.25	0.5	V
lį		V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
	CLK, J, or K	V 55V	- 1/ 0.71/			20			20	μА
lН	PRE or CLR	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 2.7 \text{ V}$		40			40		
	CLK, J, or K	V 55V	V 04V			-0.5			-0.5	mA
ΊL	PRE or CLR	V _{CC} = 5.5 V,	V _I = 0.4 V		-1.8			-1.8		
ΙΟ§		V _{CC} = 5.5 V,	$V_0 = 2.25 V$	-30		-112	-30		-112	mA
Icc		V _{CC} = 5.5 V,	See Note 1		11.5	17		11.5	17	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS. NOTE 1: ICC is measured with J, K, CLK, and PRE grounded, then with J, K, CLK, and CLR grounded.

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switching characteristics (see Figure 1)

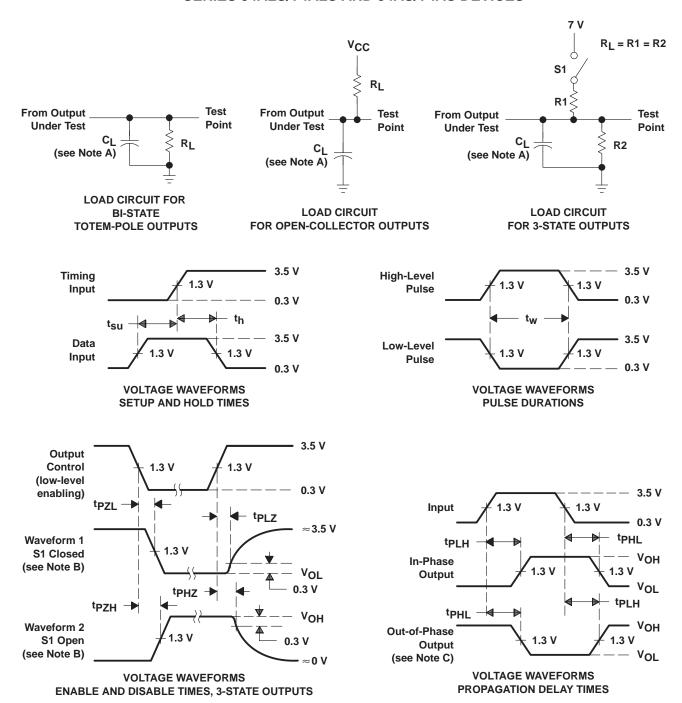
PARAMETER	FROM (INPUT)	TO (OUTPUT)	C F	L = 50 L = 500 A = MIN		t	UNIT
			MIN	MAX	MIN	MAX	
f _{max} *			90		105		MHz
t _{PLH}	PRE or CLR	0	2	9	2	8	
t _{PHL}	PRE of CLR	Q or Q	3.5	11.5	3.5	10.5	ns
t _{PLH}	CLK	Q or Q	2.5	10	2.5	9	ne
^t PHL	OLK	QOIQ	3.5	10.5	3.5	9	ns

^{*} On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: $PRR \le 1$ MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
84000012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84000012A SNJ54ALS 109AFK	Samples
8400001EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8400001EA SNJ54ALS109AJ	Samples
JM38510/37102B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37102B2A	Samples
JM38510/37102BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37102BEA	Samples
M38510/37102B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37102B2A	Samples
M38510/37102BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37102BEA	Samples
SN54ALS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS109AJ	Samples
SN74ALS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS109A	Samples
SN74ALS109ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS109A	Samples
SN74ALS109AN	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS109AN	Samples
SN74ALS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS109A	Samples
SN74AS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS109A	Samples
SN74AS109AN	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS109AN	Samples
SN74AS109ANSR	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS109A	Samples
SNJ54ALS109AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84000012A SNJ54ALS 109AFK	Samples
SNJ54ALS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8400001EA SNJ54ALS109AJ	Samples

PACKAGE OPTION ADDENDUM



24-Aug-2018

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS109A, SN74ALS109A:

Catalog: SN74ALS109A

Military: SN54ALS109A

NOTE: Qualified Version Definitions:





24-Aug-2018

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 2-Sep-2015

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS109ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS109ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

www.ti.com 2-Sep-2015



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS109ANSR	SO	NS	16	2000	367.0	367.0	38.0
SN74AS109ANSR	SO	NS	16	2000	367.0	367.0	38.0

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.